PRESS RELEASE

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TechSearch International Analyzes Substrate Shortages and Explores Potential Solutions

Substrate capacity remains tight for both flip chip ball grid array (FC-BGA) substrates and laminate-based chip scale packages (CSPs). Substrate suppliers are adding capacity to meet the demand for FC-BGA substrates for server, graphics processor, and networking applications, but demand continues to outstrip supply. Regardless of the package type—whether silicon interposer, embedded bridge, FO-on-substrate, or Redistribution Layer (RDL) interposer—a laminate substrate is used to form the package. TechSearch International quantifies the gap between manufacturing demand and capacity. The report explores options including yield improvement and substitutes under consideration to solve the crisis. RDL interposers and suppliers are discussed. Panel fan-out options and new players are described.

The new Advanced Packaging Update provides an update on the 5G rollout and the differences between the mmWave and sub-6 GHz smartphones with a look inside Apple's iPhone 12 Pro. The report also discusses semiconductor shortages, OSAT financials, and the growth of electric vehicles.

The latest APU is a 52-page report with full references and an accompanying set of 50 PowerPoint slides.

TechSearch International, Inc., founded in 1987, is a market research leader specializing in technology trends in microelectronics packaging and assembly. Multi- and single-client services encompass technology licensing, strategic planning, and market and technology analysis. TechSearch International professionals have an extensive network of more than 18,000 contacts in North America, Asia, and Europe. For more information, contact TechSearch at tel: 512-372-8887 or see www.techsearchinc.com. Follow us on twitter @Jan_TechSearch and on LinkedIn.

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